

Title (en)
METHOD FOR PRODUCING A SOULDER BUMP ON A SUBSTRATE SURFACE

Title (de)
VERFAHREN ZUM ERZEUGEN EINES LÖTHÖCKERS AUF EINER SUBSTRATBERFLÄCHE

Title (fr)
PROCEDE DE REALISATION D'UNE BILLE DE BRASURE SUR UNE FACE D'UN SUBSTRAT

Publication
EP 3743940 A1 20201202 (FR)

Application
EP 19717523 A 20190301

Priority
• FR 1852069 A 20180309
• FR 2019050468 W 20190301

Abstract (en)
[origin: WO2019170987A1] The invention relates to a serigraphy method for producing a soulder bump (50) on the front surface of a substrate (10), the method comprising the following steps: (a) forming a film (30) on the front surface; (b) forming an opening in the film (30); (c) filling the opening with a soldering material; (d) removing the film (30). The method is characterised in that step (a) is preceded by the formation of an intermediate layer (20) between the film and the front surface, the intermediate layer (20) being adapted to exhibit a force of adherence at one and/or the other interface formed with the first front surface and the film lower than the force of adherence that can be formed between the film and the first front surface. Figure 1e.

IPC 8 full level
H01L 21/60 (2006.01); **H01L 21/027** (2006.01)

CPC (source: EP US)
H01L 24/11 (2013.01 - EP US); **H01L 21/0272** (2013.01 - EP); **H01L 23/3114** (2013.01 - EP); **H01L 24/13** (2013.01 - EP); **H01L 2224/0401** (2013.01 - EP); **H01L 2224/05568** (2013.01 - EP); **H01L 2224/05647** (2013.01 - EP); **H01L 2224/11001** (2013.01 - EP); **H01L 2224/11003** (2013.01 - US); **H01L 2224/1132** (2013.01 - EP US); **H01L 2224/11474** (2013.01 - EP); **H01L 2224/11614** (2013.01 - US); **H01L 2224/11848** (2013.01 - EP); **H01L 2224/11849** (2013.01 - EP US); **H01L 2224/13023** (2013.01 - EP); **H01L 2224/13109** (2013.01 - EP); **H01L 2224/13111** (2013.01 - EP); **H01L 2224/13144** (2013.01 - EP); **H01L 2224/16225** (2013.01 - EP); **H01L 2224/73204** (2013.01 - EP)

Citation (search report)
See references of WO 2019170987A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2019170987 A1 20190912; EP 3743940 A1 20201202; FR 3078821 A1 20190913; FR 3078821 B1 20200403; US 11309269 B2 20220419; US 2021074659 A1 20210311

DOCDB simple family (application)
FR 2019050468 W 20190301; EP 19717523 A 20190301; FR 1852069 A 20180309; US 201916977987 A 20190301